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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	Z8
Core Size	8-Bit
Speed	16MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	24
Program Memory Size	2KB (2K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	125 x 8
Voltage - Supply (Vcc/Vdd)	3.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z86e3116ssc

PIN IDENTIFICATION (Continued)

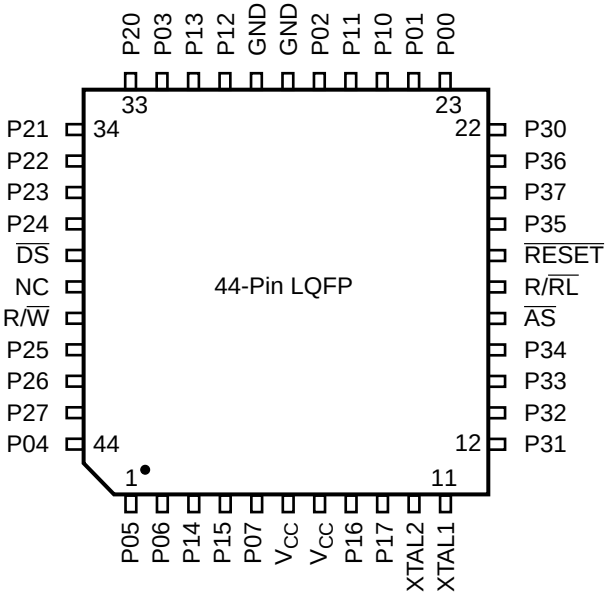


Figure 5. 44-Pin LQFP Pin Configuration
Standard Mode

Table 3. 44-Pin LQFP Pin Identification

Pin #	Symbol	Function	Direction
1–2	P05–P06	Port 0, Pins 5,6	In/Output
3–4	P14–P15	Port 1, Pins 4,5	In/Output
5	P07	Port 0, Pin 7	In/Output
6–7	V_{CC}	Power Supply	
8–9	P16–P17	Port 1, Pins 6,7	In/Output
10	XTAL2	Crystal Oscillator	Output
11	XTAL1	Crystal Oscillator	Input
12–14	P31–P33	Port 3, Pins 1,2,3	Input
15	P34	Port 3, Pin 4	Output
16	$\overline{AS}$	Address Strobe	Output
17	R/$\overline{RL}$	ROM/ROMless select	Input
18	$\overline{RESET}$	Reset	Input
19	P35	Port 3, Pin 5	Output
20	P37	Port 3, Pin 7	Output
21	P36	Port 3, Pin 6	Output
22	P30	Port 3, Pin 0	Input
23–24	P00–P01	Port 0, Pin 0,1	In/Output
25–26	P10–P11	Port 1, Pins 0,1	In/Output

Table 3. 44-Pin LQFP Pin Identification

Pin #	Symbol	Function	Direction
27	P02	Port 0, Pin 2	In/Output
28–29	GND	Ground	
30–31	P12–P13	Port 1, Pins 2,3	In/Output
32	P03	Port 0, Pin 3	In/Output
33–37	P20–4	Port 2, Pins 0,1,2,3,4	In/Output
38	$\overline{DS}$	Data Strobe	Output
39	NC	No Connection	
40	R/$\overline{W}$	Read/Write	Output
41–43	P25–P27	Port 2, Pins 5,6,7	In/Output
44	P04	Port 0, Pin 4	In/Output

PIN IDENTIFICATION (Continued)

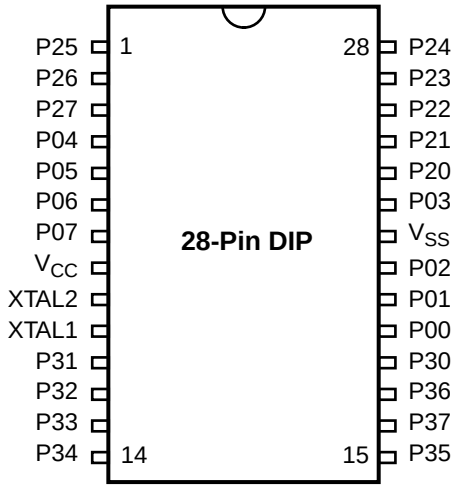


Figure 9. Standard Mode 28-Pin DIP/SOIC Pin Configuration

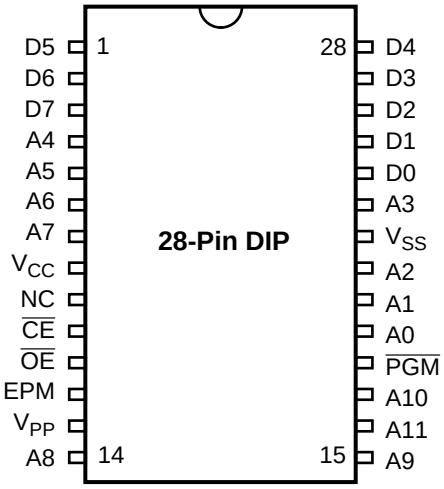


Figure 10. EPROM Programming Mode 28-Pin DIP/SOIC Pin Configuration

Table 7. 28-Pin DIP/SOIC/PLCC Pin Identification*

Pin #	Symbol	Function	Direction
1–3	P25–P27	Port 2, Pins 5,6,	In/Output
4–7	P04–P07	Port 0, Pins 4,5,6,7	In/Output
8	V_{CC}	Power Supply	
9	XTAL2	Crystal Oscillator	Output
10	XTAL1	Crystal Oscillator	Input
11–13	P31–P33	Port 3, Pins 1,2,3	Input
14–15	P34–P35	Port 3, Pins 4,5	Output
16	P37	Port 3, Pin 7	Output
17	P36	Port 3, Pin 6	Output
18	P30	Port 3, Pin 0	Input
19–21	P00–P02	Port 0, Pins 0,1,2	In/Output
22	V_{SS}	Ground	
23	P03	Port 0, Pin 3	In/Output
24–28	P20–P24	Port 2, Pins 0,1,2,3,4	In/Output

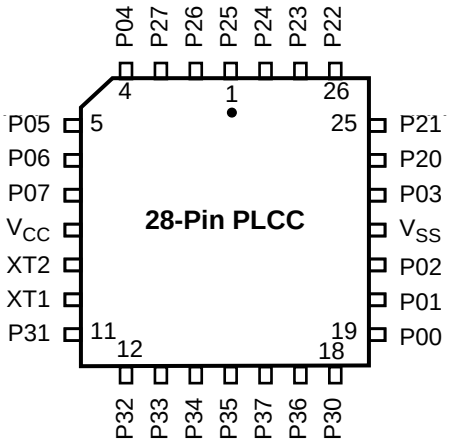


Figure 11. Standard Mode 28-Pin PLCC Pin Configuration

DC ELECTRICAL CHARACTERISTICS (Continued)

			T_A= 0 °C to +70 °C					
Sym	Parameter	V_{CC} Note [3]	Min	Max	Typical @ 25°C	Units	Conditions	Notes
I_{CC}	Supply Current	3.5V		20	7	mA	@ 16 MHz	4,5
		5.5V		25	20	mA	@ 16 MHz	4,5
I_{CC1}	Standby Current Halt Mode	3.5V		8	3.7	mA	V_{IN} = 0V, V_{CC}	4,5
		5.5V		8	3.7	mA	@ 16 MHz	4,5
		3.5V		7.0	2.9	mA	Clock Divide by	4,5
		5.5V		7.0	2.9	mA	16 @ 16 MHz	4,5
I_{CC2}	Standby Current Stop Mode	3.5V		10	2	µA	V_{IN} = 0V, V_{CC}	6,11
		5.5V		10	3	µA	V_{IN} = 0V, V_{CC}	6,11
		3.5V		800	600	µA	V_{IN} = 0V, V_{CC}	6,11,14
		5.5V		800	600	µA	V_{IN} = 0V, V_{CC}	6,11,14
I_{ALL}	Auto Latch Low Current	3.5V	0.7	8	2.4	µA	0V <V_{IN}<V_{CC}	9
		5.5V	1.4	15	4.7	µA	0V <V_{IN}<V_{CC}	9
I_{ALH}	Auto Latch High Current	3.5V	-0.6	-5	-1.8	µA	0V<V_{IN}<V_{CC}	9
		5.5V	-1	-8	-3.8	µA	0V<V_{IN}<V_{CC}	9
T_{POR}	Power On Reset	3.5V	3.0	24	7	ms		
		5.5V	2.0	13	4	ms		
V_{LV}	Auto Reset Voltage		2.3	3.1	2.9	V		1,7

Notes:

1. Device does function down to the Auto Reset voltage.
2. GND=0V
3. The V_{CC} voltage specification of 5.5V guarantees 5.0V ± 0.5V and the V_{CC} voltage specification of 3.5V guarantees only 3.5V.
4. All outputs unloaded, I/O pins floating, inputs at rail.
5. CL1= CL2 = 22 pF
6. Same as note [4] except inputs at $V_{CC.}$
7. Max. temperature is 70°C.
8. STD Mode (not Low EMI Mode)
9. Auto Latch (mask option) selected
10. For analog comparator inputs when analog comparators are enabled.
11. Clock must be forced Low, when XTAL1 is clock driven and XTAL2 is floating.
12. Typicals are at V_{CC} = 5.0V and V_{CC} = 3.5V
13. Z86E40 only
14. WDT running

Sym	Parameter	V_{CC} Note [3]	Min	Max	Typical @ 25°C	Units	Conditions	Notes
			T_A=–40 °C to +105 °C					
V_{CH}	Clock Input High Voltage	4.5V 5.5V	0.7 V_{CC} 0.7 V_{CC}	V_{CC}+0.3 V_{CC}+0.3	2.5 2.5	V V	Driven by External Clock Generator	
V_{CL}	Clock Input Low Voltage	4.5V 5.5V	GND-0.3 GND-0.3	0.2 V_{CC} 0.2 V_{CC}	1.5 1.5	V V	Driven by External Clock Generator	
V_{IH}	Input High Voltage	4.5V 5.5V	0.7 V_{CC} 0.7 V_{CC}	V_{CC}+0.3 V_{CC}+0.3	2.5 2.5	V V		
V_{IL}	Input Low Voltage	4.5V 5.5V	GND-0.3 GND-0.3	0.2 V_{CC} 0.2 V_{CC}	1.5 1.5	V V		
V_{OH}	Output High Voltage Low EMI Mode	4.5V 5.5V	V_{CC} -0.4 V_{CC} -0.4		4.8 4.8	V V	I_{OH} = – 0.5 mA I_{OH} = – 0.5 mA	8 8
V_{OH1}	Output High Voltage	4.5V 4.5V	V_{CC} -0.4 V_{CC} -0.4		4.8 4.8	V V	I_{OH} = -2.0 mA I_{OH} = -2.0 mA	8 8
V_{OL}	Output Low Voltage Low EMI Mode	4.5V 5.5V		0.4 0.4	0.2 0.2	V V	I_{OL} = 1.0 mA I_{OL} = 1.0 mA	
V_{OL1}	Output Low Voltage	4.5V 5.5V		0.4 0.4	0.1 0.1	V V	I_{OL} = + 4.0 mA I_{OL} = +4.0 mA	8 8
V_{OL2}	Output Low Voltage	4.5V 5.5V		1.2 1.2	0.5 0.5	V V	I_{OL} = + 12 mA I_{OL} = + 12 mA	8 8
V_{RH}	Reset Input High Voltage	3.5V 5.5V	.8 V_{CC} .8 V_{CC}	V_{CC} V_{CC}	1.7 2.1	V V		13 13
V_{OLR}	Reset Output Low Voltage	3.5V 5.5V		0.6 0.6	0.3 0.2	V V	I_{OL} = 1.0 mA I_{OL} = 1.0 mA	13 13
V_{OFFSET}	Comparator Input Offset Voltage	4.5V 5.5V		25 25	10 10	mV mV		
V_{ICR}	Input Common Mode Voltage Range	4.5V 5.5V	0 0	V_{CC}-1.5V V_{CC}-1.5V		V V		10 10
I_{IL}	Input Leakage	4.5V 5.5V	-1 -1	2 2	<1 <1	µA µA	V_{IN} = 0V, V_{CC} V_{IN} = 0V, V_{CC}	
I_{OL}	Output Leakage	4.5V 5.5V	-1 -1	2 2	<1 <1	µA µA	V_{IN} = 0V, V_{CC} V_{IN} = 0V, V_{CC}	
I_{IR}	Reset Input Current	4.5V 5.5V	-18 -18	-180 -180	-112 -112	µA µA		
I_{CC}	Supply Current	4.5V 5.5V		25 25	20 20	mA mA	@ 16 MHz @ 16 MHz	4,5 4,5
I_{CC1}	Standby Current Halt Mode	4.5V 5.5V		8 8	3.7 3.7	mA mA	V_{IN} = 0V, V_{CC} @ 16 MHz V_{IN} = 0V, V_{CC} @ 16 MHz	4,5 4,5
I_{CC2}	Standby Current (Stop Mode)	4.5V 5.5V		10 10	2 3	µA µA	V_{IN} = 0V, V_{CC} V_{IN} = 0V, V_{CC}	6,11,14 6,11,14
I_{ALL}	Auto Latch Low Current	4.5V 5.5V	1.4 1.4	20 20	4.7 4.7	µA µA	0V < V_{IN} < V_{CC} 0V < V_{IN} < V_{CC}	9 9

Additional Timing Table

				T_A = -40 °C to +105 °C 16 MHz				
No	Symbol	Parameter	V_{CC} Note [6]	Min	Max	Units	Conditions	Notes
1	TpC	Input Clock Period	3.5V	62.5	DC	ns		1,7,8
			5.5V	62.5	DC	ns		1,7,8
2	TrC,TfC	Clock Input Rise & Fall Times	3.5V		15	ns		1,7,8
			5.5V		15	ns		1,7,8
3	TwC	Input Clock Width	3.5V	31		ns		1,7,8
			5.5V	31		ns		1,7,8
4	TwTinL	Timer Input Low Width	3.5V	70		ns		1,7,8
			5.5V	70		ns		1,7,8
5	TwTinH	Timer Input High Width	3.5V	5TpC				1,7,8
			5.5V	5TpC				1,7,8
6	TpTin	Timer Input Period	3.5V	8TpC				1,7,8
			5.5V	8TpC				1,7,8
7	TrTin, TfTin	Timer Input Rise & Fall Timer	3.5V		100	ns		1,7,8
			5.5V		100	ns		1,7,8
8A	TwIL	Int. Request Low Time	3.5V	70		ns		1,2,7,8
			5.5V	70		ns		1,2,7,8
8B	TwIL	Int. Request Low Time	3.5V	5TpC				1,3,7,8
			5.5V	5TpC				1,3,7,8
9	TwIH	Int. Request Input High Time	3.5V	5TpC				1,2,7,8
			5.5V					
10	Twsm	STOP Mode Recovery Width Spec	3.5V	12		ns		4,8
			5.5V	12		ns		4,8
11	Tost	Oscillator Startup Time	3.5V		5TpC			4,8
			5.5V		5TpC			4,8
12	Twdt	Watch-Dog Timer Delay Time Before Timeout	3.5V	10		ms	D0 = 0	5,11
			5.5V	5		ms	D1 = 0	5,11
			3.5V	20		ms	D0 = 1	5,11
			5.5V	10		ms	D1 = 0	5,11
			3.5V	40		ms	D0 = 0	5,11
			5.5V	20		ms	D1 = 1	5,11
			3.5V	160		ms	D0 = 1	5,11
			5.5V	80		ms	D1 = 1	5,11

Notes:

1. Timing Reference uses 0.7 V_{CC} for a logic 1 and 0.2 V_{CC} for a logic 0.
2. Interrupt request via Port 3 (P31–P33)
3. Interrupt request via Port 3 (P30)
4. SMR-D5 = 1, POR STOP Mode Delay is on
5. Reg. WDTMR
6. The V_{CC} voltage spec. of 5.5V guarantees 5.0V ± 0.5V.
7. SMR D1 = 0
8. Maximum frequency for internal system clock is 4 MHz when using XTAL divide-by-one mode.
9. For RC and LC oscillator, and for oscillator driven by clock driver.
10. Standard Mode (not Low EMI output ports)
11. Using internal RC

PIN FUNCTIONS

EPROM Programming Mode

D7–D0 Data Bus. The data can be read from or written to external memory through the data bus.

A11–A0 Address Bus. During programming, the EPROM address is written to the address bus.

V_{CC} Power Supply. This pin must supply 5V during the EPROM read mode and 6V during other modes.

$\overline{CE}$ Chip Enable (active Low). This pin is active during EPROM Read Mode, Program Mode, and Program Verify Mode.

$\overline{OE}$ Output Enable (active Low). This pin drives the direction of the Data Bus. When this pin is Low, the Data Bus is output, when High, the Data Bus is input.

EPM EPROM Program Mode. This pin controls the different EPROM Program Mode by applying different voltages.

V_{PP} Program Voltage. This pin supplies the program voltage.

$\overline{PGM}$ Program Mode (active Low). When this pin is Low, the data is programmed to the EPROM through the Data Bus.

Application Precaution

The production test-mode environment may be enabled accidentally during normal operation if excessive noise surges above V_{CC} occur on pins XTAL1 and $\overline{RESET}$.

In addition, processor operation of Z8 OTP devices may be affected by excessive noise surges on the V_{PP}, $\overline{CE}$, $\overline{EPM}$, $\overline{OE}$ pins while the microcontroller is in Standard Mode.

Recommendations for dampening voltage surges in both test and OTP mode include the following:

- Using a clamping diode to V_{CC}
- Adding a capacitor to the affected pin

Standard Mode

XTAL Crystal 1 (time-based input). This pin connects a parallel-resonant crystal, ceramic resonator, LC, RC network, or external single-phase clock to the on-chip oscillator input.

XTAL2 Crystal 2 (time-based output). This pin connects a parallel-resonant crystal, ceramic resonator, LC, or RC network to the on-chip oscillator output.

R/$\overline{W}$ Read/Write (output, write Low). The R/$\overline{W}$ signal is Low when the CCP is writing to the external program or data memory (Z86E40 only).

$\overline{RESET}$ Reset (input, active Low). Reset will initialize the MCU. Reset is accomplished either through Power-On, Watch-Dog Timer reset, STOP-Mode Recovery, or external reset. During Power-On Reset and Watch-Dog Timer Reset, the internally generated reset drives the reset pin low for the POR time. Any devices driving the reset line must be open-drain in order to avoid damage from a possible conflict during reset conditions. Pull-up is provided internally. After the POR time, $\overline{RESET}$ is a Schmitt-triggered input.

To avoid asynchronous and noisy reset problems, the Z86E40 is equipped with a reset filter of four external clocks (4TpC). If the external reset signal is less than 4TpC in duration, no reset occurs. On the fifth clock after the reset is detected, an internal RST signal is latched and held for an internal register count of 18 external clocks, or for the duration of the external reset, whichever is longer. During the reset cycle, $\overline{DS}$ is held active Low while $\overline{AS}$ cycles at a rate of TpC/2. Program execution begins at location 000CH, 5–10 TpC cycles after $\overline{RESET}$ is released. For Power-On Reset, the reset output time is 5 ms. The Z86E40 does not reset WDTMR, SMR, P2M, and P3M registers on a STOP-Mode Recovery operation.

$\overline{ROMless}$ (input, active Low). This pin, when connected to GND, disables the internal ROM and forces the device to function as a Z86C90/C89 ROMless Z8. (Note that, when left unconnected or pulled High to V_{CC}, the device functions normally as a Z8 ROM version).

Note: When using in ROM Mode in High EMI (noisy) environment, the ROMless pins should be connected directly to V_{CC}.

Port 2 (P27–P20). Port 2 is an 8-bit, bidirectional, CMOS-compatible I/O port. These eight I/O lines can be configured under software control as an input or output, independently. All input buffers are Schmitt-triggered. Bits programmed as outputs can be globally programmed as either push-pull or open-drain. Low EMI output buffers can be globally programmed by the software. When used as an I/O port, Port 2 can be placed under handshake control.

In Handshake Mode, Port 3 lines P31 and P36 are used as handshake control lines. The handshake direction is determined by the configuration (input or output) assigned to bit 7 of Port 2 (Figure 20).

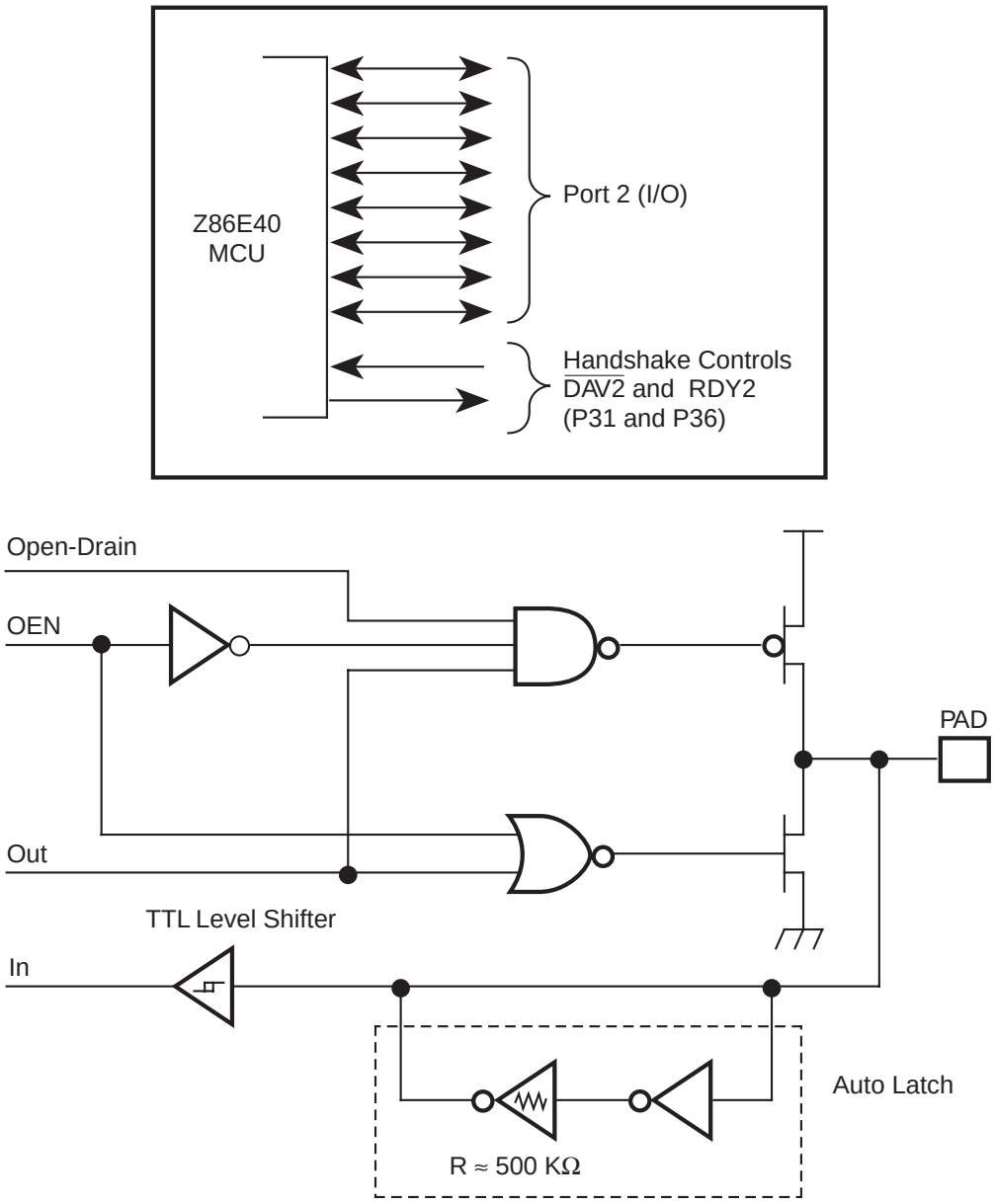


Figure 20. Port 2 Configuration

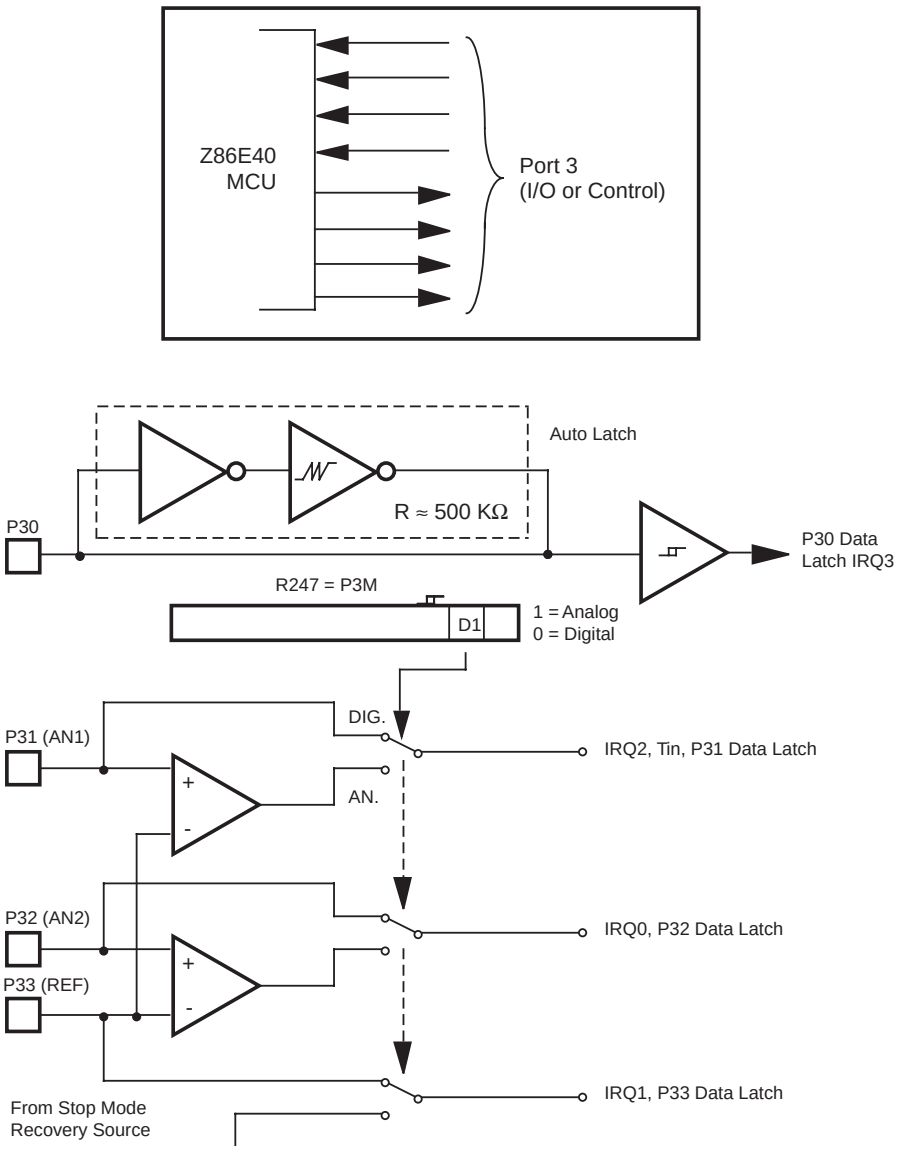


Figure 21. Port 3 Configuration

Table 9. Port 3 Pin Assignments

Pin	I/O	CTC1	Analog	Interrupt	P0 HS	P1 HS	P2 HS	Ext
P30	IN			IRQ3				
P31	IN	T_{IN}	AN1	IRQ2		D/R		
P32	IN		AN2	IRQ0	D/R			
P33	IN		REF	IRQ1		D/R		
P34	OUT		AN1-Out			R/D		/DM
P35	OUT				R/D			
P36	OUT	T_{OUT}				R/D		
P37	OUT		An2-Out					

FUNCTIONAL DESCRIPTION (Continued)

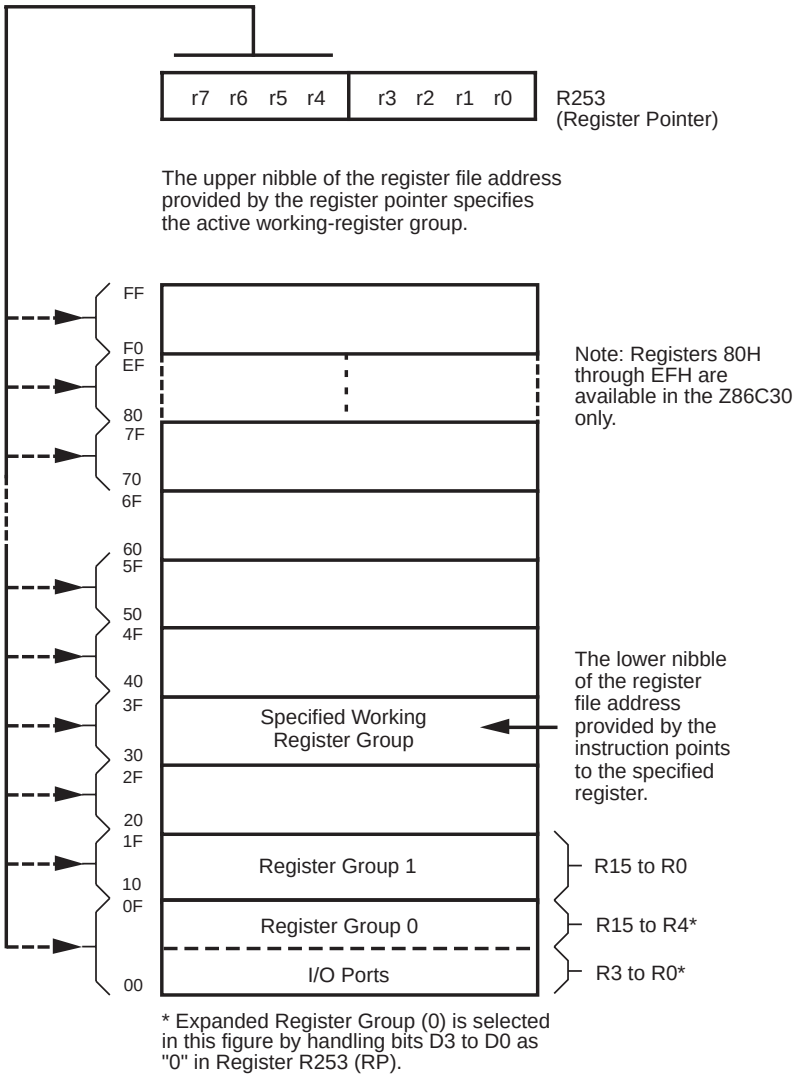


Figure 25. Register Pointer

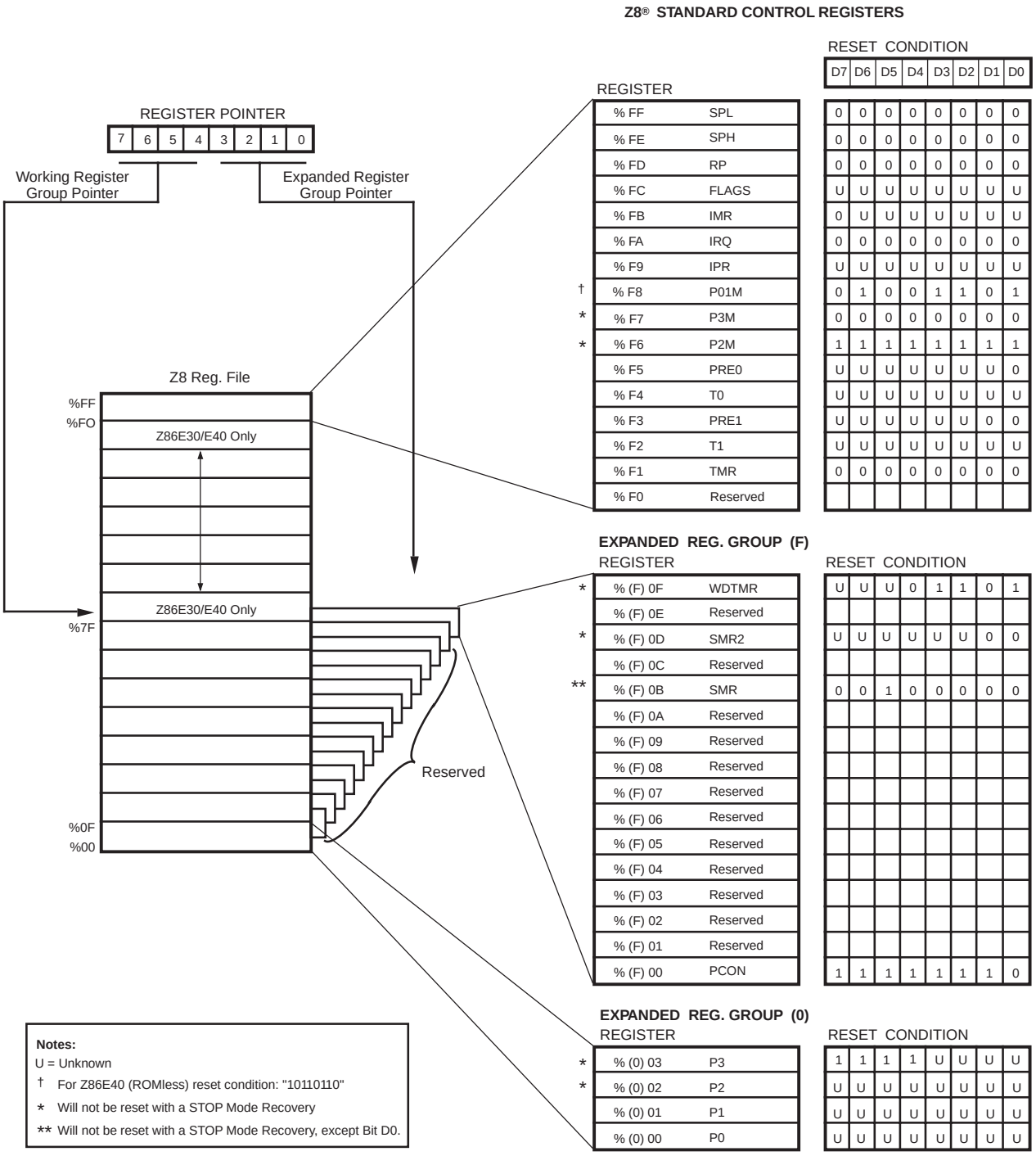


Figure 26. Expanded Register File Architecture

When more than one interrupt is pending, priorities are resolved by a programmable priority encoder that is controlled by the Interrupt Priority Register (IPR). An interrupt machine cycle is activated when an interrupt request is granted. Thus, disabling all subsequent interrupts, saves the Program Counter and Status Flags, and then branches to the program memory vector location reserved for that interrupt. All interrupts are vectored through locations in the program memory. This memory location and the next byte contain the 16-bit starting address of the interrupt service routine for that particular interrupt request.

To accommodate polled interrupt systems, interrupt inputs are masked and the interrupt request register is polled to determine which of the interrupt requests need service.

An interrupt resulting from AN1 is mapped into IRQ2, and an interrupt from AN2 is mapped into IRQ0. Interrupts IRQ2 and IRQ0 may be rising, falling or both edge triggered, and are programmable by the user. The software may poll to identify the state of the pin.

Programming bits for the Interrupt Edge Select are located in bits D7 and D6 of the IRQ Register (R250). The configuration is shown in Table 11.

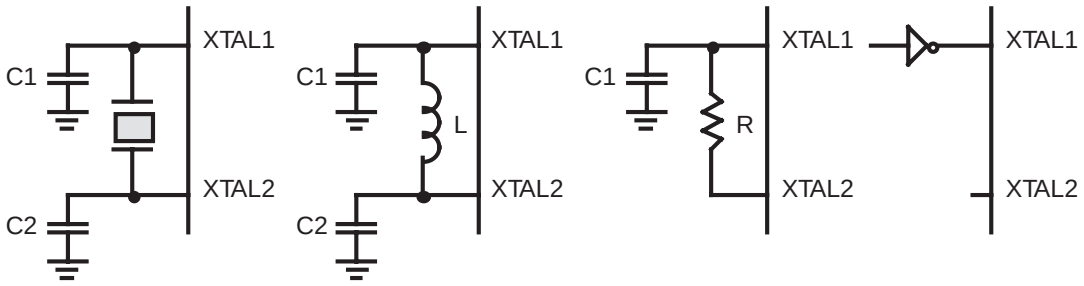
Table 11. IRQ Register Configuration

IRQ		Interrupt Edge	
D7	**D6**	**P31**	**P32**
0	0	F	F
0	1	F	R
1	0	R	F
1	1	R/F	R/F

Notes:
F = Falling Edge
R = Rising Edge

Clock. The on-chip oscillator has a high-gain, parallel-resonant amplifier for connection to a crystal, RC, ceramic resonator, or any suitable external clock source (XTAL1 = Input, XTAL2 = Output). The crystal should be AT cut, 10 KHz to 16 MHz max, with a series resistance (RS) less than or equal to 100 Ohms.

The crystal should be connected across XTAL1 and XTAL2 using the vendor's recommended capacitor values from each pin directly to device pin Ground. The RC oscillator option can be selected in the programming mode. The RC oscillator configuration must be an external resistor connected from XTAL1 to XTAL2, with a frequency-setting capacitor from XTAL1 to Ground (Figure 29).



Ceramic Resonator or Crystal
C1, C2 = 47 pF TYP *
F = 8 MHz

LC
C1, C2 = 22 pF

L = 130 µH *
F = 3 MHz *

RC
@ 5V Vcc (TYP)

C1 = 100 pF
R = 2K
F = 6 MHz

External Clock

* Typical value including pin parasitics

Figure 29. Oscillator Configuration

FUNCTIONAL DESCRIPTION (Continued)

Power-On Reset (POR). A timer circuit clocked by a dedicated on-board RC oscillator is used for the Power-On Reset (POR) timer function. The POR timer allows V_{CC} and the oscillator circuit to stabilize before instruction execution begins.

The POR timer circuit is a one-shot timer triggered by one of three conditions:

1. Power fail to Power OK status
2. Stop-Mode Recovery (if D5 of SMR=0)
3. WDT time-out

The POR time is a nominal 5 ms. Bit 5 of the STOP mode Register (SMR) determines whether the POR timer is bypassed after STOP-Mode Recovery (typical for an external clock and RC/LC oscillators with fast start up times).

HALT. Turns off the internal CPU clock, but not the XTAL oscillation. The counter/timers and external interrupt IRQ0, IRQ1, and IRQ2 remain active. The device is recovered by interrupts, either externally or internally generated. An interrupt request must be executed (enabled) to exit HALT Mode. After the interrupt service routine, the program continues from the instruction after the HALT.

In order to enter STOP or HALT Mode, it is necessary to first flush the instruction pipeline to avoid suspending execution in mid-instruction. To do this, the user must execute a NOP (Opcode=FFH) immediately before the appropriate sleep instruction, that is:

```
FF      NOP     ; clear the pipeline
6F      STOP    ; enter STOP Mode
                or
FF      NOP     ; clear the pipeline
7F      HALT    ; enter HALT Mode
```

STOP. This instruction turns off the internal clock and external crystal oscillation and reduces the standby current to 10 microamperes or less. STOP Mode is terminated by one of the following resets: either by WDT time-out, POR, a Stop-Mode Recovery Source, which is defined by the SMR register or external reset. This causes the processor to restart the application program at address 000CH.

Port Configuration Register (PCON). The PCON register configures the ports individually; comparator output on Port 3, open-drain on Port 0 and Port 1, low EMI on Ports 0, 1, 2 and 3, and low EMI oscillator. The PCON register is located in the expanded register file at Bank F, location 00 (Figure 30).

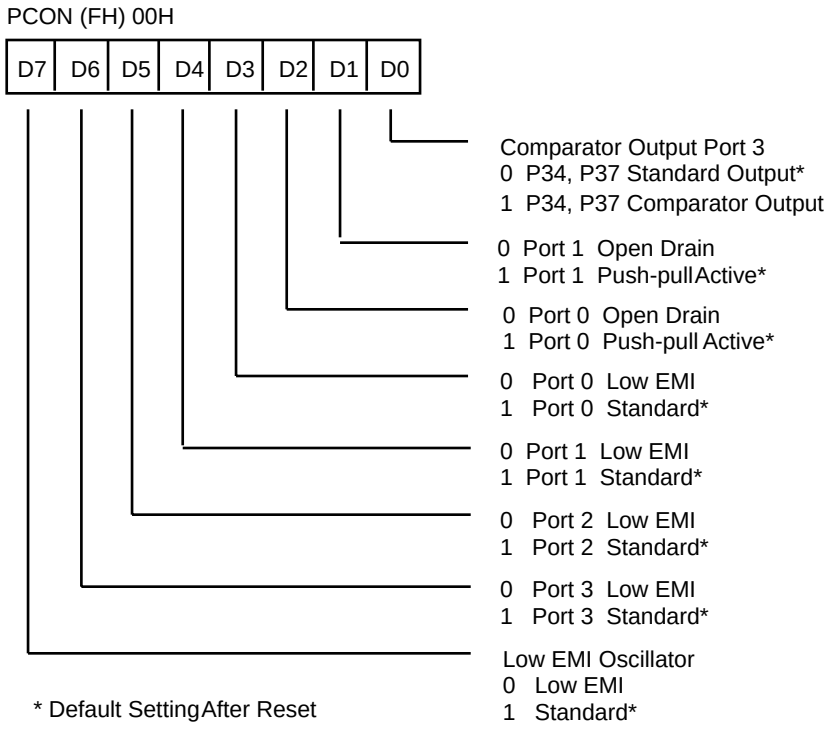


Figure 30. Port Configuration Register (PCON) (Write Only)

Comparator Output Port 3 (D0). Bit 0 controls the comparator output in Port 3. A “1” in this location brings the comparator outputs to P34 and P37, and a “0” releases the Port to its standard I/O configuration. The default value is 0.

Port 1 Open-Drain (D1). Port 1 can be configured as an open-drain by resetting this bit (D1=0) or configured as push-pull active by setting this bit (D1=1). The default value is 1.

Port 0 Open-Drain (D2). Port 0 can be configured as an open-drain by resetting this bit (D2=0) or configured as push-pull active by setting this bit (D2=1). The default value is 1.

Low EMI Port 0 (D3). Port 0 can be configured as a Low EMI Port by resetting this bit (D3=0) or configured as a Standard Port by setting this bit (D3=1). The default value is 1.

Low EMI Port 1 (D4). Port 1 can be configured as a Low EMI Port by resetting this bit (D4=0) or configured as a Standard Port by setting this bit (D4=1). The default value is 1. **Note:** The emulator does not support Port 1 low EMI mode and must be set D4 = 1.

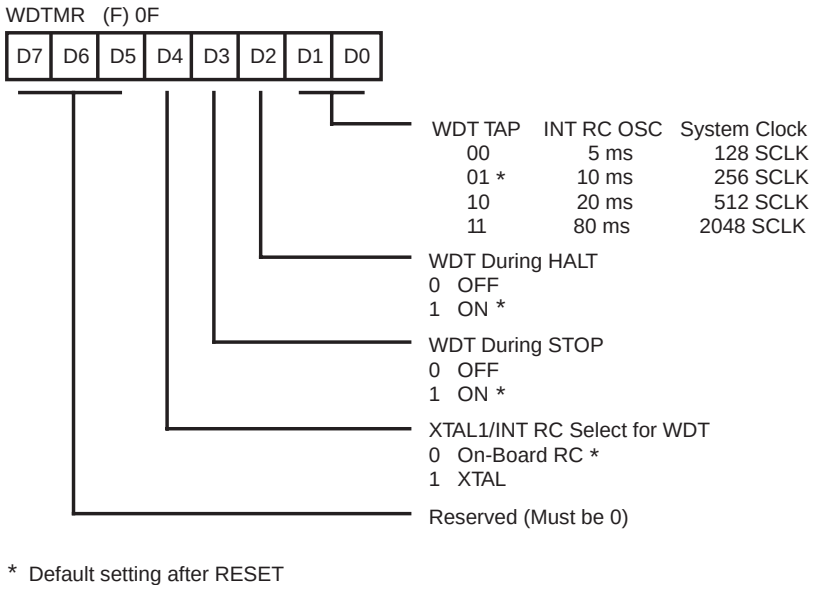
Low EMI Port 2 (D5). Port 2 can be configured as a Low EMI Port by resetting this bit (D5=0) or configured as a Standard Port by setting this bit (D5=1). The default value is 1.

Low EMI Port 3 (D6). Port 3 can be configured as a Low EMI Port by resetting this bit (D6=0) or configured as a Standard Port by setting this bit (D6=1). The default value is 1.

Low EMI OSC (D7). This bit of the PCON Register controls the low EMI noise oscillator. A “1” in this location configures the oscillator with standard drive. While a “0” configures the oscillator with low noise drive, however, it does not affect the relationship of SCLK and XTAL. The low EMI mode will reduce the drive of the oscillator (OSC). The default value is 1. **Note:** 4 MHz is the maximum external clock frequency when running in the low EMI oscillator mode.

Stop-Mode Recovery Register (SMR). This register selects the clock divide value and determines the mode of Stop-Mode Recovery (Figure 31). All bits are Write Only except bit 7 which is a Read Only. Bit 7 is a flag bit that is hardware set on the condition of STOP Recovery and reset by a power-on cycle. Bit 6 controls whether a low or high level is required from the recovery source. Bit 5 controls the reset delay after recovery. Bits 2, 3, and 4 of the SMR register specify the Stop-Mode Recovery Source. The SMR is located in Bank F of the Expanded Register Group at address 0BH.

cycles from the execution of the first instruction after Power-On Reset, Watch-Dog reset or a STOP-Mode Recovery (Figures 33 and 34). After this point, the register cannot be modified by any means, intentional or otherwise. The WDTMR cannot be read and is located in Bank F of the Expanded Register Group at address location 0FH.



* Default setting after RESET

Figure 33. Watch-Dog Timer Mode Register Write Only

FUNCTIONAL DESCRIPTION (Continued)

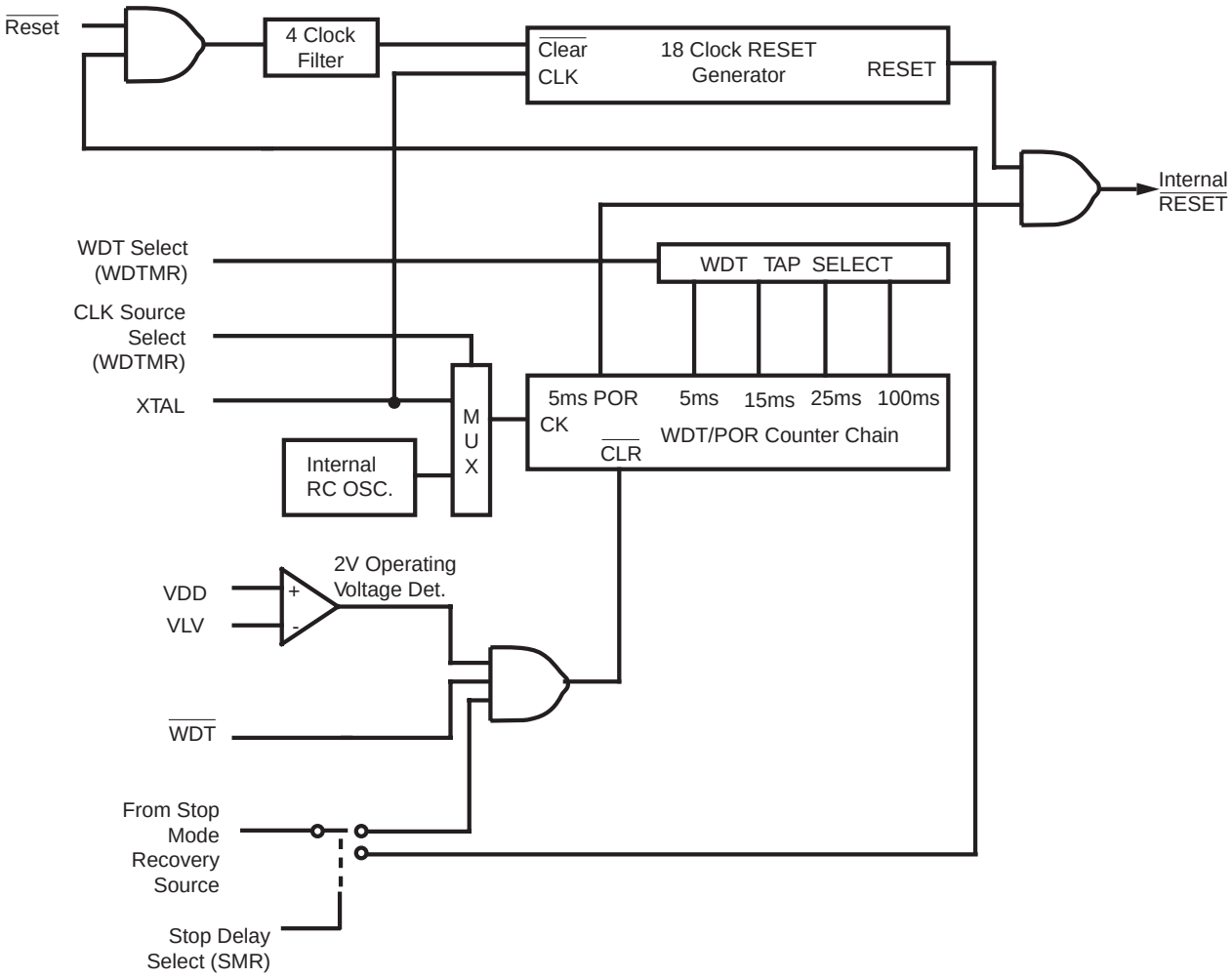


Figure 34. Resets and WDT

FUNCTIONAL DESCRIPTION (Continued)

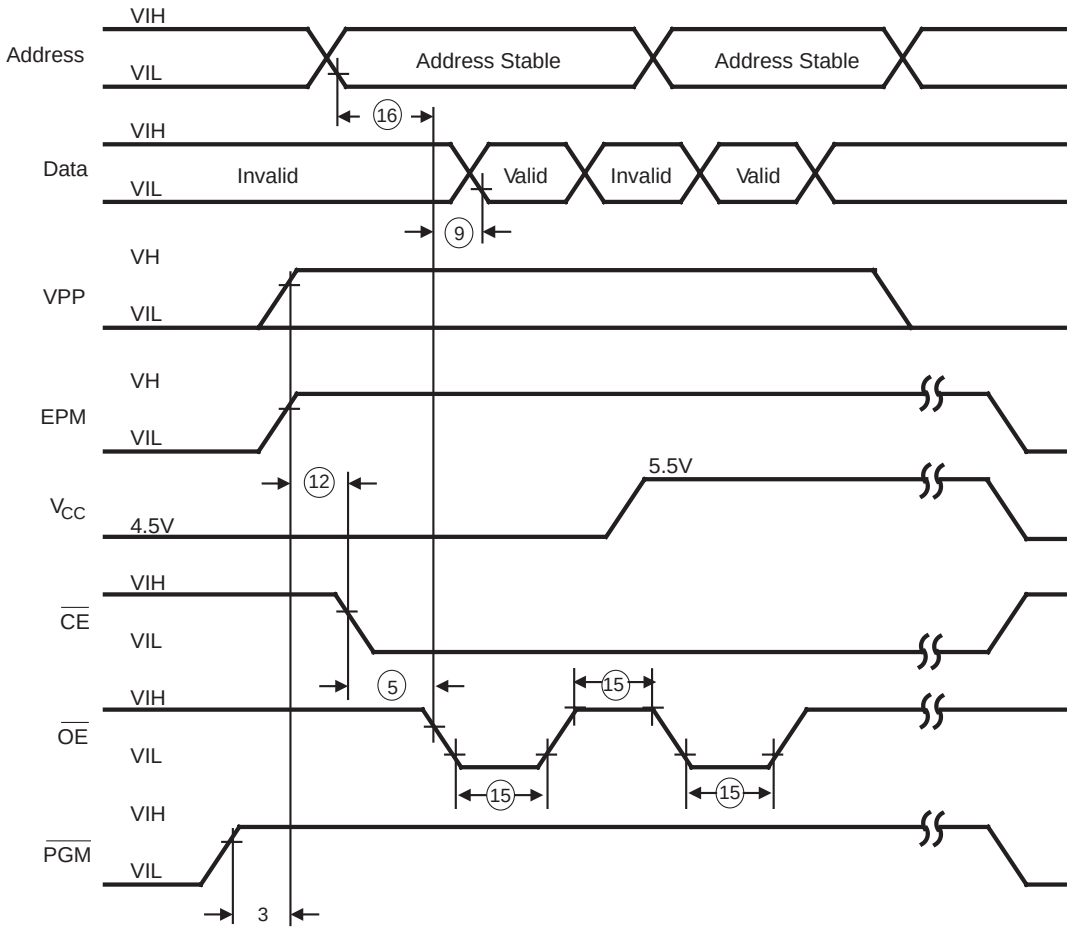


Figure 36. EPROM Read Mode Timing Diagram

Z86E40 TIMING DIAGRAMS (Continued)

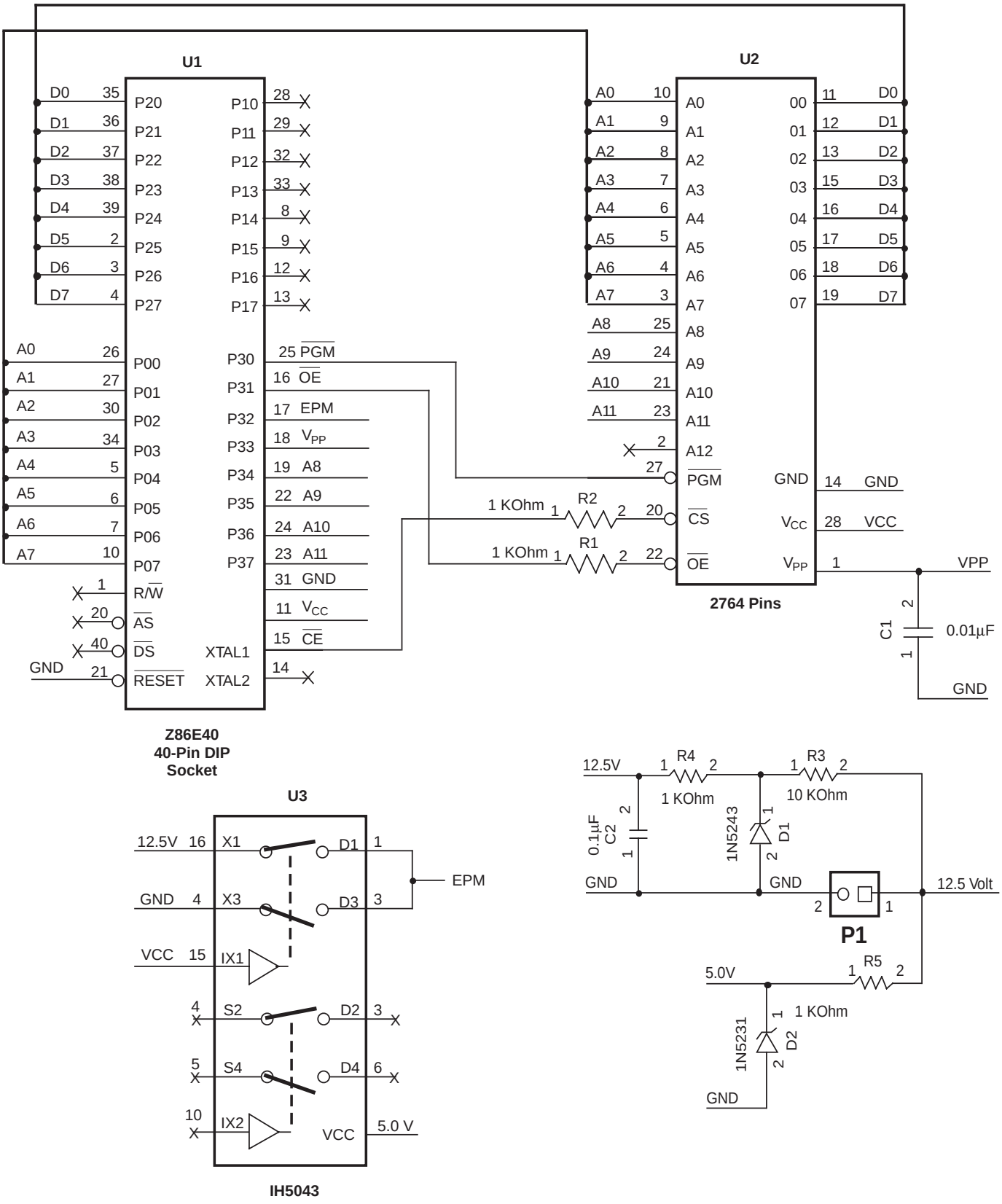


Figure 38. Z86E40 Z8 OTP Programming Adapter
For use with Standard EPROM Programmers

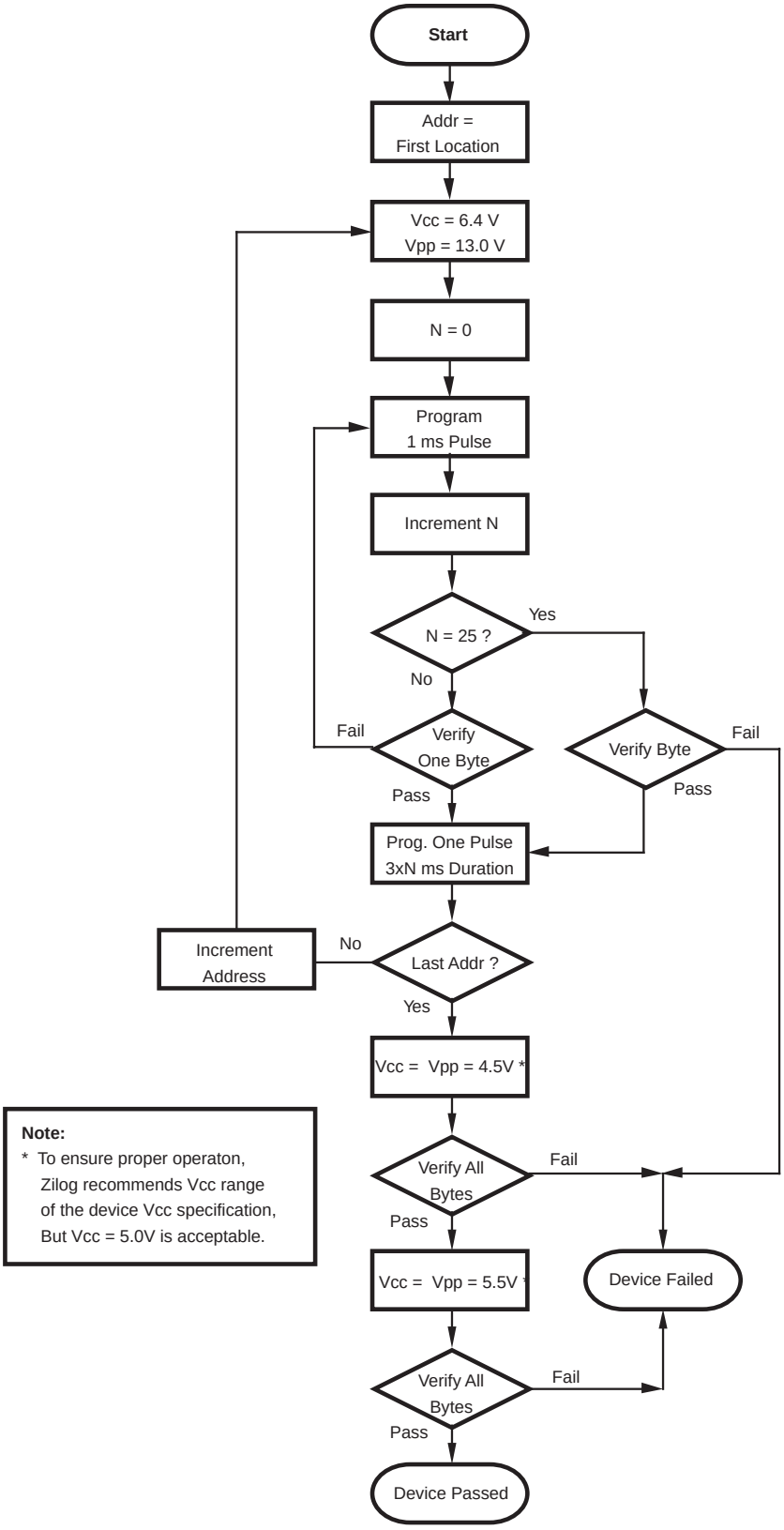


Figure 40. Z86E40 Programming Algorithm

Z8 CONTROL REGISTER DIAGRAMS (Continued)

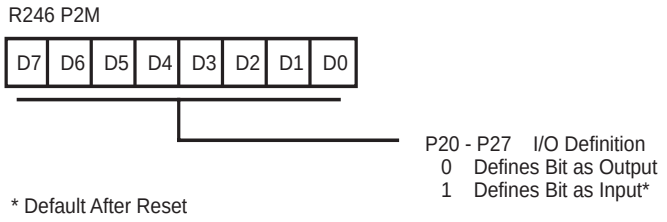


Figure 51. Port 2 Mode Register
F6H: Write Only

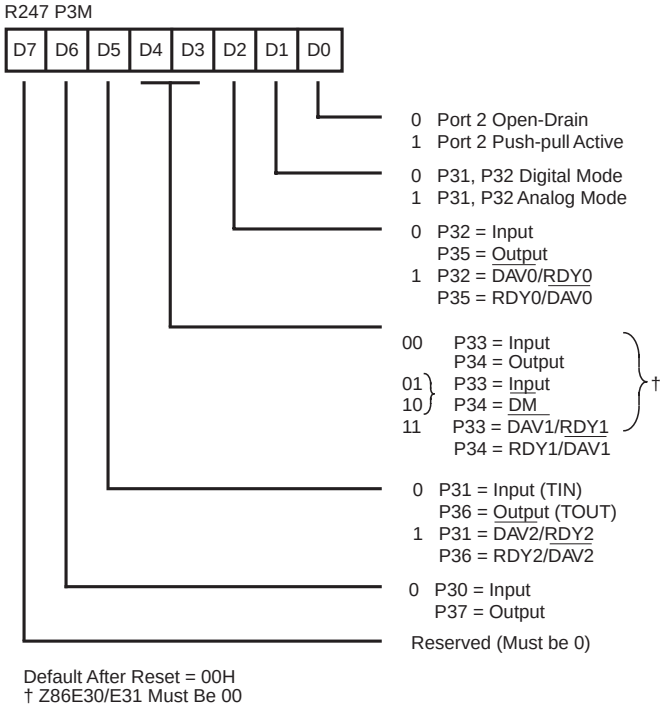


Figure 52. Port 3 Mode Register
F7H: Write Only

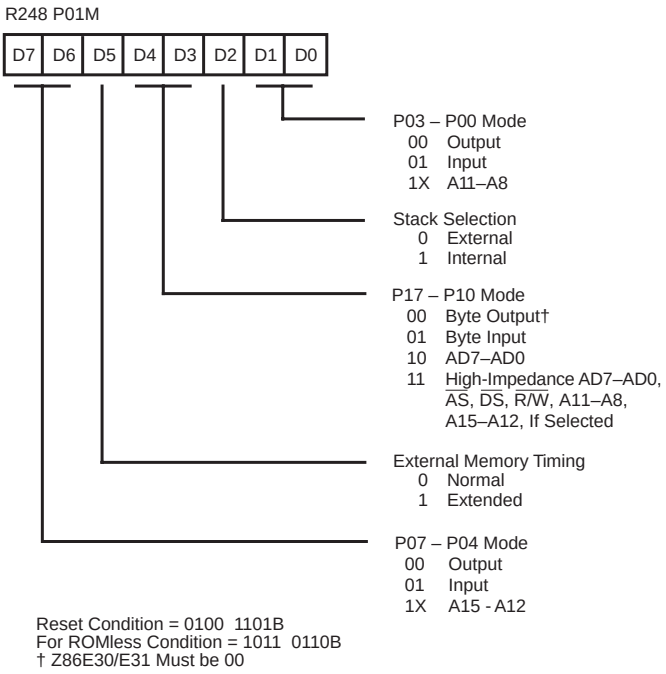


Figure 53. Port 0 and 1 Mode Register
F8H: Write Only
Z86E30/E31 Only

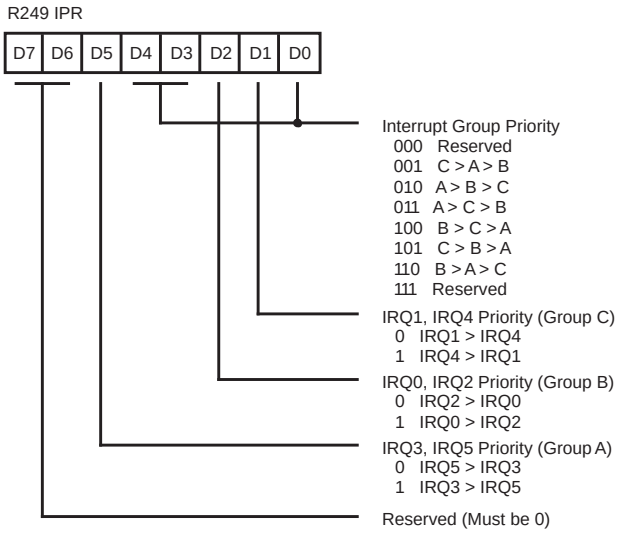
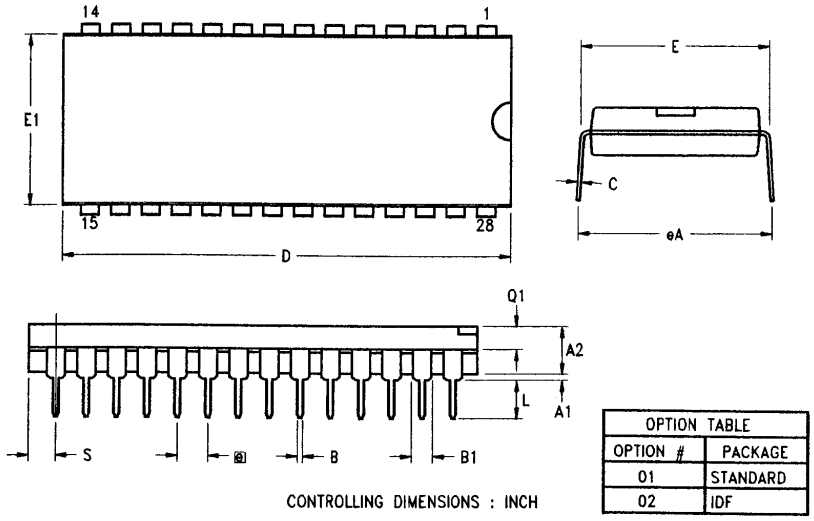


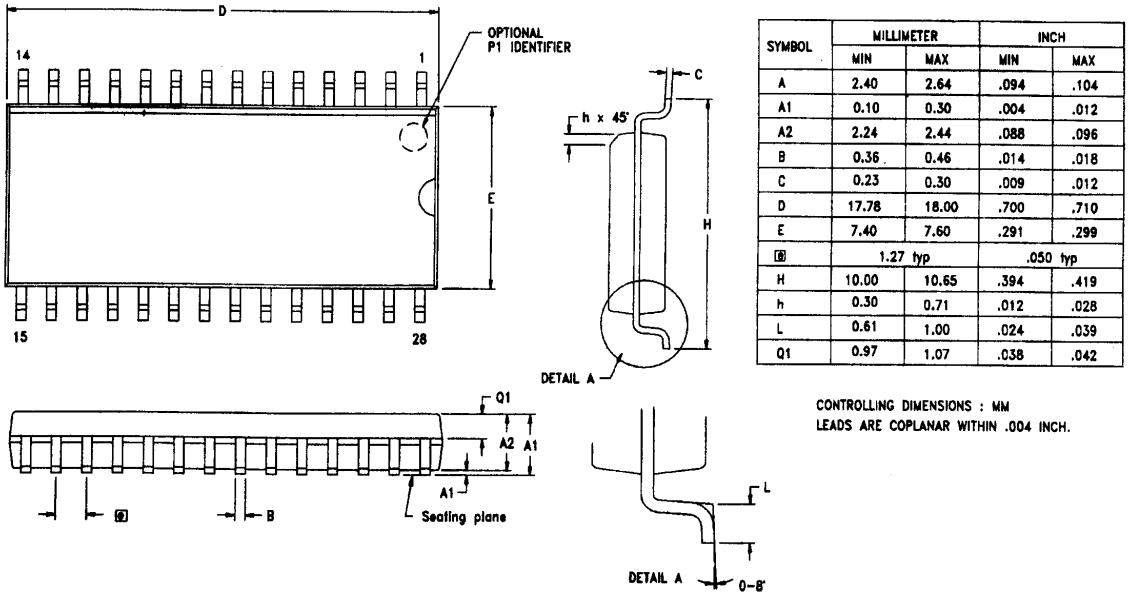
Figure 54. Interrupt Priority Register
F9H: Write Only



OPTION TABLE	
OPTION #	PACKAGE
01	STANDARD
02	IDF

SYMBOL	OPT #	MILLIMETER		INCH	
		MIN	MAX	MIN	MAX
A1		0.51	1.02	.020	.040
A2		3.18	3.94	.125	.155
B		0.38	0.53	.015	.021
B1	01	1.40	1.65	.055	.065
	02	1.14	1.40	.045	.055
C		0.23	0.38	.009	.015
D	01	36.58	37.34	1.440	1.470
	02	35.31	35.94	1.390	1.415
E		15.24	15.75	.600	.620
E1	01	13.59	14.10	.535	.555
	02	12.83	13.08	.505	.515
e		2.54 TYP		.100 TYP	
eA		15.49	16.76	.610	.660
L		3.05	3.81	.120	.150
Q1	01	1.52	1.91	.060	.075
	02	1.52	1.78	.060	.070
S	01	1.52	2.29	.060	.090
	02	1.02	1.52	.040	.060

Figure 64. 28-Pin DIP Package Diagram



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A	2.40	2.64	.094	.104
A1	0.10	0.30	.004	.012
A2	2.24	2.44	.088	.096
B	0.36	0.46	.014	.018
C	0.23	0.30	.009	.012
D	17.78	18.00	.700	.710
E	7.40	7.60	.291	.299
e	1.27 typ		.050 typ	
H	10.00	10.65	.394	.419
h	0.30	0.71	.012	.028
L	0.61	1.00	.024	.039
Q1	0.97	1.07	.038	.042

Figure 65. 28-Pin SOIC Package Diagram